

PART INFORMATION

Mfg Item Number	MC9S12DB128MFU
Mfg Item Name	QFP 80 14*14*2.2P0.65

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2015-01-01
Response Document ID	6019K10532D003A1.22
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	No
Pb Free	No
HalogenFree	No
Plating Indicator	e0
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MC9S12DB128MFU
Mfg Item Name	QFP 80 14*14*2.2P0.65
Version	ALL
Weight	0.935500
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	220 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0079						g				
Epoxy Die Attach		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0.0000002	g	3	0.0003	0	0
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00149459	g	189188	18.9188	1597	0.1597
Epoxy Die Attach		Lead/Lead Compounds	Lead	7439-92-1		0.00000005	g	6	0.0006	0	0
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00640534	g	810803	81.0803	6846	0.6846
Die Encapsulant	0.679						g				
Die Encapsulant		Antimony/Antimony Compounds	Antimony trioxide	1309-64-4		0.01363364	g	20079	2.0079	14573	1.4573
Die Encapsulant		Flame Retardants	Bromophenol, formaldehyde, epichlorohydrin polymer	68541-56-0		0.01363364	g	20079	2.0079	14573	1.4573
Die Encapsulant		Plastics/polymers	4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl diglycidyl ether	85954-11-6		0.02726728	g	40158	4.0158	29147	2.9147
Die Encapsulant		Plastics/polymers	Poly(o-cresyl glycidyl ether)-co-formaldehyde	20690-92-2		0.02726728	g	40158	4.0158	29147	2.9147
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00167472	g	2761	0.2761	2003	0.2003
Die Encapsulant		Lead/Lead Compounds	Lead	7439-92-1		0.00009893	g	13	0.0013	0	0.0009
Die Encapsulant		Metals	Magnesium Aluminum Hydroxide Carbonate	11097-69-9		0.00068172	g	1004	0.1004	728	0.0728
Die Encapsulant		Solvents, additives, and other materials	Triphenyl phosphine	603-35-0		0.0009861	g	1305	0.1305	947	0.0947
Die Encapsulant		Solvents, additives, and other materials	[3,4-Epoxycyclohexylethyl]methoxyllane	3388-04-3		0.0074982	g	11043	1.1043	8015	0.8015
Die Encapsulant		Plastics/polymers	Phenol p-xylylene dimethyl ether copolymer	2634-02-6		0.05453456	g	80316	8.0316	58294	5.8294
Die Encapsulant		Glass	Silicon dioxide	7631-86-9		0.26585702	g	391542	39.1542	284201	28.4201
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.26585702	g	391542	39.1542	284187	28.4187
Copper Lead Frame	0.2015						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.19423692	g	963955	96.3955	207628	20.7628
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.00016624	g	825	0.0825	177	0.0177
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.00473255	g	23500	2.35	5061	0.5061
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00003426	g	170	0.017	36	0.0036
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.002015	g	10000	1	2153	0.2153
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.0006045	g	300	0.03	64	0.0064
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00025188	g	1250	0.125	269	0.0269
Bonding Wire	0.0017						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0017	g	1000000	100	1817	0.1817
Silicon Semiconductor Die	0.038						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00076	g	20000	2	812	0.0812
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.03724	g	980000	98	39807	3.9807
Lead Frame Plating	0.0074						g				
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00037	g	50000	5	395	0.0395
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.00703	g	950000	95	7514	0.7514

LINKS

MCD LINK

Freescale website <http://www.freescale.com>

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf

Conflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf

FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MC9S12DB128MFU_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MC9S12DB128MFU_IPC1752A.xml